

**32/36-bit Data Bus**  
**Dynamic RAM Card**

MF14M1-L1XATXX  
 MF14M1-L2XATXX  
 MF18M1-L1XATXX  
 MF18M1-L2XATXX

Connector Type

**Two-piece 88-pin**

**DESCRIPTION**

These DRAM CARDS are developed based on JEIDA DRAM CARD GUIDELINE Ver. 2.0. These cards are made using industry standard 1 M × 4 and 1 M × 1 Dynamic RAM and interface IC's in TSOP.

**FEATURES**

- All inputs except RAS inputs are buffered.
- Standard card size : 54mm (W) × 85.6mm (L) × 3.3mm (T)
- 88pin 2 piece connector type.
- RAS only refresh mode. CAS before RAS refresh mode and Page mode functions are available.
- Extended refresh is available. (128ms/1024cycle)

**APPLICATIONS**

Main/expansion memory unit for Personal Computer, Laser-Printer, FAX etc.

**PRODUCT LIST**

Product No.	Item Type name	Memory capacity	Data Bus width (bits)	Access time (tRAC) (ns)	Connector type	Number of pins	Outline drawing
No. 1	MF14M1-L17ATXX	4 MB	32	70	Two-piece	88	88P-001
No. 2	MF14M1-L18ATXX		(without parity)	80			
No. 3	MF14M1-L27ATXX		36	70			
No. 4	MF14M1-L28ATXX		(with parity)	80			
No. 5	MF18M1-L17ATXX	8 MB	32	70			
No. 6	MF18M1-L18ATXX		(without parity)	80			
No. 7	MF18M1-L27ATXX		36	70			
No. 8	MF18M1-L28ATXX		(with parity)	80			

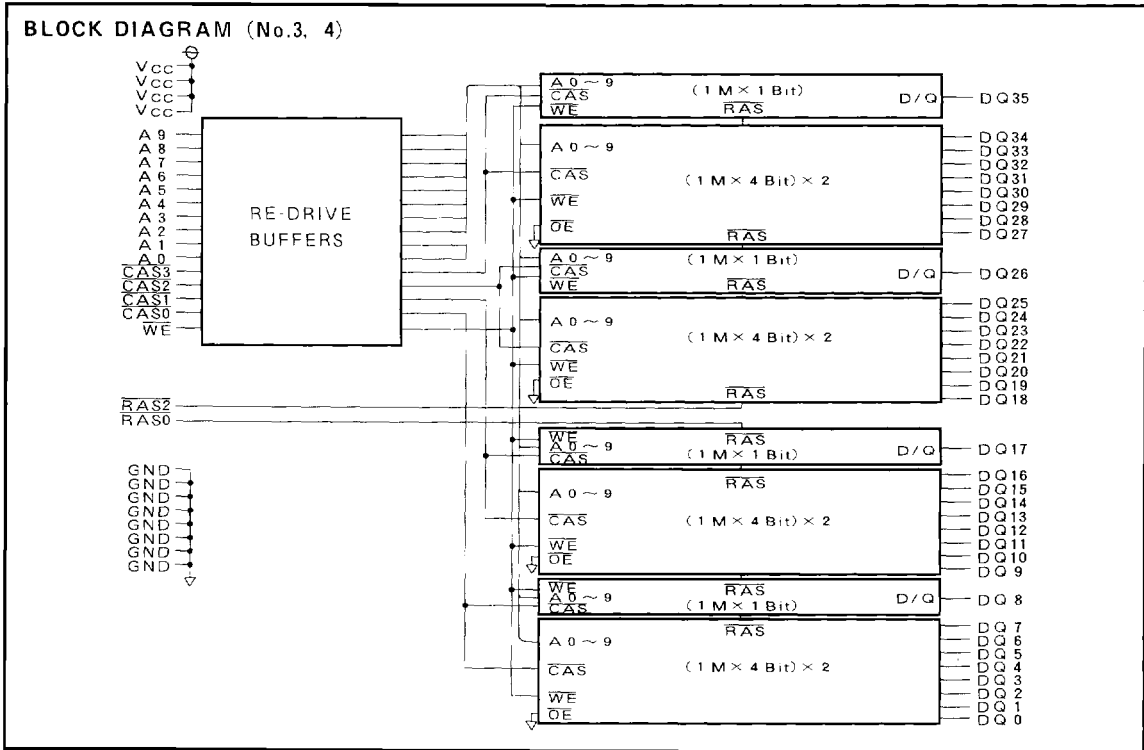
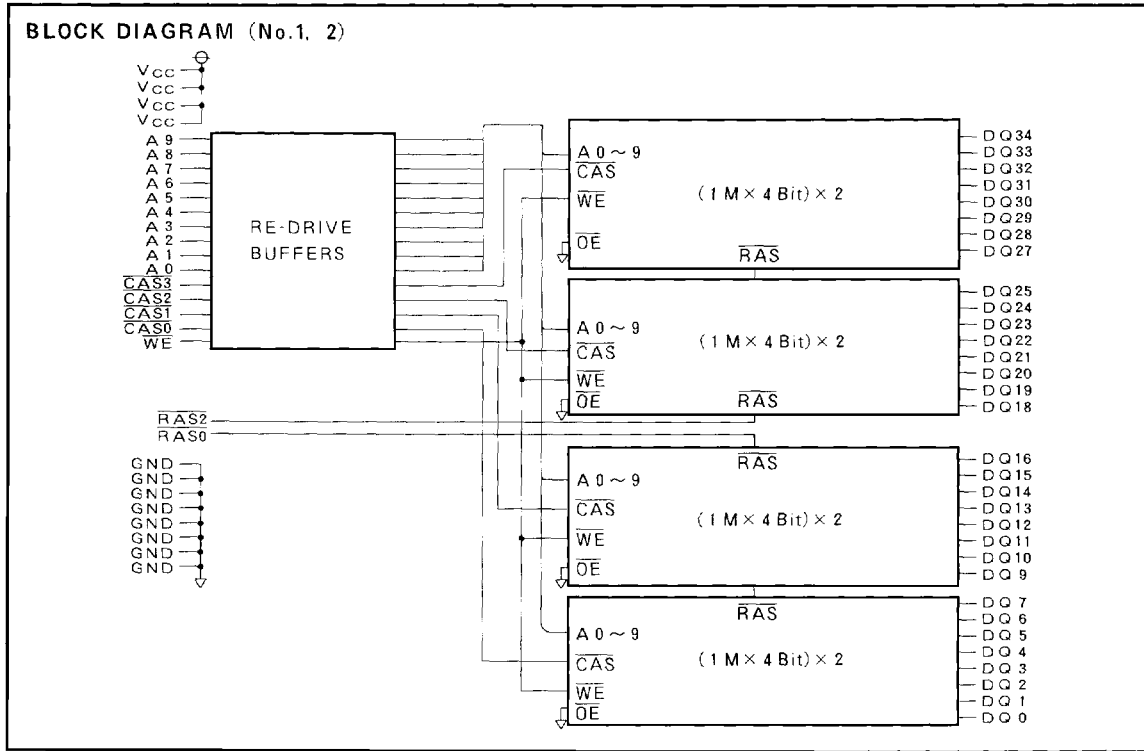
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PIN ASSIGNMENT

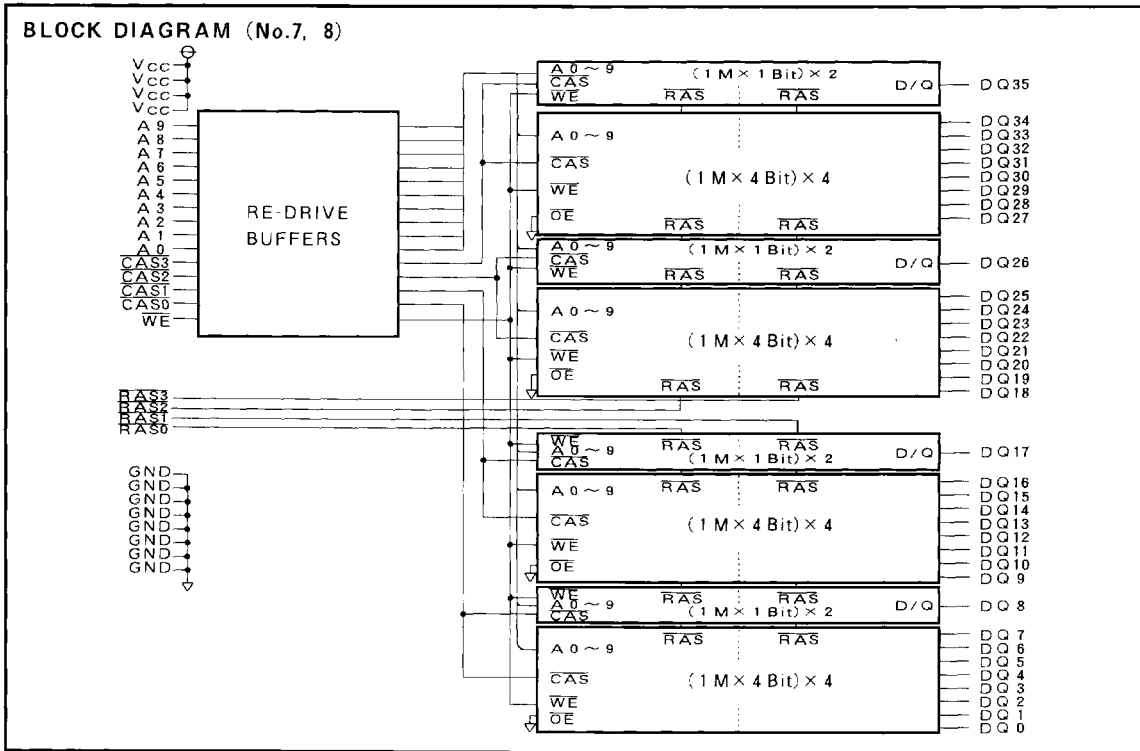
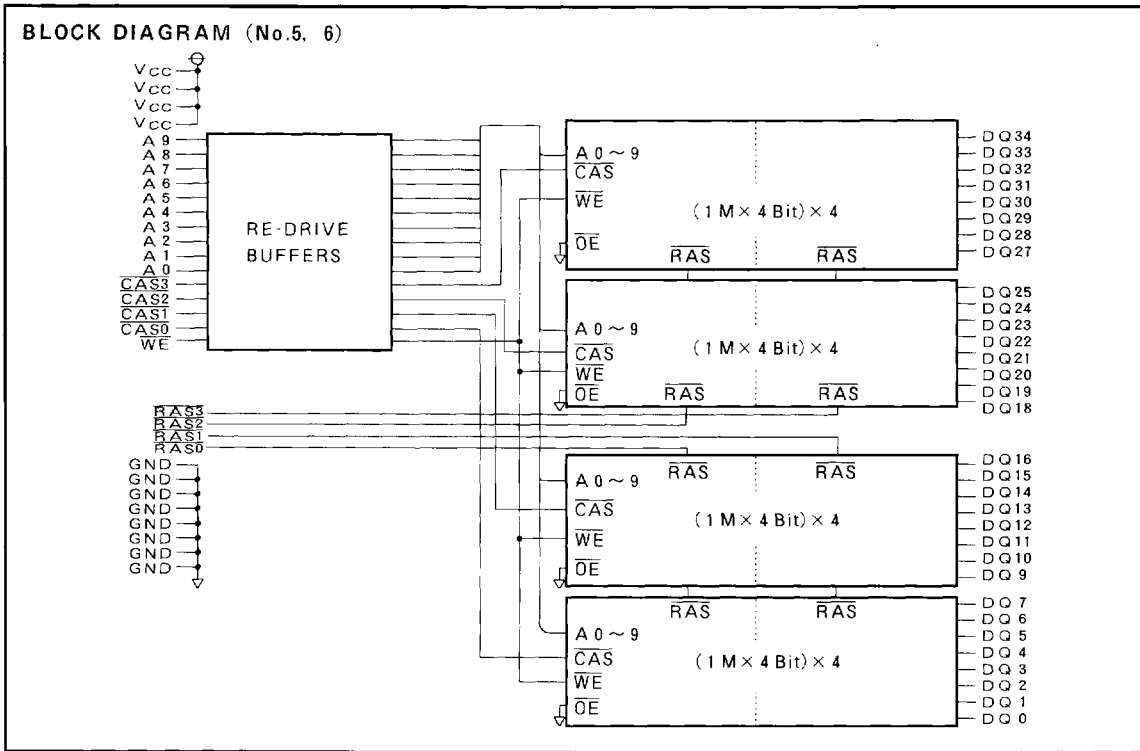
Pin No.	Symbol	Function	Pin No.	Symbol	Function
1	GND	Ground	45	GND	Ground
2	DQ 0	Data I/O	46	DQ18	Data I/O
3	DQ 1		47	DQ19	
4	DQ 2		48	DQ20	
5	DQ 3		49	DQ21	
6	DQ 4		50	DQ22	
7	DQ 5		51	DQ23	
8	DQ 6		52	DQ24	
9	V <sub>cc</sub>	Power supply voltage	53	DQ25	Data I/O (NC for No. 1, 2, 5, 6)
10	DQ7	Data I/O	54	DQ26	
11	NC	No connection	55	NC	No connection
12	DQ 8	Data I/O (NC for No. 1, 2, 5, 6)	56	GND	Ground
13	A 0	Address input	57	A 1	Address input
14	A 2		58	A 3	
15	V <sub>cc</sub>		Power supply voltage	59	
16	A 4	Address input	60	A 7	No connection
17	NC	No connection	61	A 9	
18	A 6	Address input	62	NC	
19	A 8		63	GND	Ground
20	NC	No connection	64	NC	No connection
21	NC		65	RAS 1	Row address strobe 1 (NC for No. 1, 2, 3, 4)
22	RAS 0	Row address strobe 0	66	CAS 2	Column address strobe 2
23	CAS 0	Column address strobe 0	67	GND	Ground
24	CAS 1	Column address strobe 1	68	CAS 3	Column address strobe 3
25	NC	No connection	69	RAS 3	Row address strobe 3 (NC for No. 1, 2, 3, 4)
26	RAS 2	Row address strobe 2	70	WE	Write enable
27	V <sub>cc</sub>	Power supply voltage	71	PD 1	Presence detect 1
28	PD 2	Presence detect 2	72	PD 3	Presence detect 3
29	PD 4	Presence detect 4	73	GND	Ground
30	PD 6	Presence detect 6	74	PD 5	Presence detect 5
31	NC	No connection	75	PD 7	Presence detect 7
32	NC		76	PD 8	Presence detect 8
33	DQ17	Data I/O (NC for No. 1, 2, 5, 6)	77	NC	No connection
34	DQ 9	Data I/O	78	NC	
35	NC	No connection	79	DQ35	Data I/O (NC for No. 1, 2, 5, 6)
36	DQ10	Data I/O	80	DQ27	Data I/O
37	V <sub>cc</sub>	Power supply voltage	81	DQ28	
38	DQ11	Data I/O	82	DQ29	
39	DQ12		83	DQ30	
40	DQ13		84	DQ31	
41	DQ14		85	DQ32	
42	DQ15		86	DQ33	
43	DQ16		87	DQ34	
44	GND		Ground	88	GND

PD Pin Table

Product No.	PD 1	PD 2	PD 3	PD 4	PD 5	PD 6	PD 7	PD 8
No. 1, No. 3	GND	NC	GND	GND	NC	GND	NC	NC
No. 2, No. 4	GND	NC	GND	GND	NC	NC	GND	NC
No. 5, No. 7	GND	NC	GND	GND	GND	GND	NC	NC
No. 6, No. 8	GND	NC	GND	GND	GND	NC	GND	NC



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FUNCTION TABLE

Operation	input					input/output		Refresh	Note
	$\overline{\text{RAS}}$	$\overline{\text{CAS}}$	$\overline{\text{WE}}$	Row Address	Column Address	input	output		
Read	ACT	ACT	NAC	APD	APD	OPN	VLD	YES	Page mode identical
Early write	ACT	ACT	ACT	APD	APD	VLD	OPN	YES	
$\overline{\text{RAS}}$ only refresh	ACT	NAC	DNC	APD	DNC	DNC	OPN	YES	
CAS before $\overline{\text{RAS}}$ refresh	ACT	ACT	NAC	DNC	DNC	DNC	OPN	YES	
Standby	NAC	DNC	DNC	DNC	DNC	DNC	OPN	NO	

Note 1 : ACT : active, NAC : nonactive, DNC : don't care, VLD : valid, APD : applied, OPN : open  
 Don't be active more than two RASs at the same time.

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
$V_{CC}$	Supply voltage	With respect to GND	-0.5~7	V
$V_I$	Input voltage		-0.5~ $V_{CC}+0.5$ (7V max.)	V
$V_O$	Output voltage		-0.5~7	V
$I_O$	Output current		50	mA
$P_d$	Power dissipation	$T_a=25^\circ\text{C}$	8	W
$T_{opr}$	Operating temperature		0~55	$^\circ\text{C}$
$T_{stg}$	Storage temperature		-40~80	$^\circ\text{C}$

RECOMMENDED OPERATING CONDITIONS ( $T_a=0\sim55^\circ\text{C}$ , unless otherwise noted): (Note 2)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
$V_{CC}$	Supply voltage	4.75	5	5.25	V
GND	Supply voltage	0	0	0	V
$V_{IL}$	Low input voltage	0		0.8	V
$V_{IH}$	High input voltage	$0.7 \times V_{CC}$		$V_{CC}$	V

Note 2 : With respect to GND

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ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 0 ~ 55°C, V<sub>CC</sub> = 5 V ± 5%, GND = 0 V) : (Note 3)

Symbol	Parameter	Test condition	Limits																Unit
			Min.				Typ.	Max.											
			No. 1, No. 2	No. 3, No. 4	No. 5, No. 6	No. 7, No. 8		No. 1	No. 2	No. 3	No. 4	No. 5	No. 6	No. 7	No. 8				
V <sub>OH</sub>	High output voltage	I <sub>OH</sub> = -5 mA	2.4					V <sub>CC</sub>								V			
V <sub>OL</sub>	Low output voltage	I <sub>OL</sub> = 4.2 mA	0					0.4								V			
I <sub>OZ</sub>	Off-stage output current	0 V ≤ V <sub>OUT</sub> ≤ V <sub>CC</sub>	-10	-10	-20	-20		10	10	10	10	20	20	20	20	20	20	μA	
I <sub>I</sub>	Input current	0 V ≤ V <sub>IN</sub> ≤ V <sub>CC</sub> Other input pins = 0 V	-40	-60	-40	-60		40	40	60	60	40	40	60	60	60	60	μA	
I <sub>CC1(AV)</sub>	Average supply current from V <sub>CC</sub> , operating (Note 4, 5)	$\overline{\text{RAS}}$ , $\overline{\text{CAS}}$ cycling t <sub>RC</sub> = t <sub>WC</sub> = min, output open						800	700	1120	980	820	730	1150	1010		mA		
I <sub>CC2(AV)</sub>	Supply current from V <sub>CC</sub> , standby	$\overline{\text{RAS}} = \overline{\text{CAS}} = V_{IH}$ , output open						20	20	28	28	36	36	52	52		mA		
		$\overline{\text{RAS}} = \overline{\text{CAS}} \geq V_{CC} - 0.2V$ , other input pins $\geq V_{CC} - 0.2V$ or $\leq 0.2V$ , output open						5	5	6	6	9	9	10	10				
I <sub>CC3(AV)</sub>	Average supply current from V <sub>CC</sub> , refreshing (Note 4)	$\overline{\text{RAS}}$ cycling, $\overline{\text{CAS}} = V_{IH}$ t <sub>RC</sub> = min, output open						800	700	1120	980	820	730	1150	1010		mA		
I <sub>CC4(AV)</sub>	Average supply current from V <sub>CC</sub> , Page-Mode (Note 4, 5)	$\overline{\text{RAS}} = V_{IL}$ , $\overline{\text{CAS}}$ cycling t <sub>RC</sub> = min, output open						960	900	1240	1140	980	930	1270	1170		mA		
I <sub>CC6(AV)</sub>	Average supply current from V <sub>CC</sub> , CAS before RAS refresh mode (Note 4)	$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh cycling t <sub>RC</sub> = min, output open						720	620	1040	900	740	650	1070	930		mA		

Note 3 : Current flowing into a CARD is positive, out is negative.

4 : I<sub>CC1(AV)</sub>, I<sub>CC3(AV)</sub>, I<sub>CC4(AV)</sub> and I<sub>CC6(AV)</sub> are dependent on cycle rate. Specified values are obtained at the fastest cycle rate.

5 : I<sub>CC1(AV)</sub> and I<sub>CC4(AV)</sub> are dependent on output loading. Specified values are obtained with the outputs open.

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SWITCHING CHARACTERISTICS ( $T_a = 0 \sim 55^\circ\text{C}$ ,  $V_{CC} = 5\text{V} \pm 5\%$ ,  $\text{GND} = 0\text{V}$ ): (Note 6)

Symbol	Parameter	Limits				Unit
		No. 2, No. 4, No. 6, No. 8		No. 1, No. 3, No. 5, No. 7		
		Min.	Max.	Min.	Max.	
t <sub>CAC</sub>	Access time from $\overline{\text{CAS}}$ (Note 7, 8)		30		27	ns
t <sub>RAC</sub>	Access time from $\overline{\text{RAS}}$ (Note 7, 9)		80		70	ns
t <sub>CAA</sub>	Column Address access time (Note 7, 10)		50		45	ns
t <sub>OFF</sub>	Output disable time after $\overline{\text{CAS}}$ high (Note 11)	0	30	0	25	ns

Note 6 : An initial pause of 500  $\mu\text{sec}$  is required after power-up followed by any 8  $\overline{\text{RAS}}$  or  $\overline{\text{RAS}}/\overline{\text{CAS}}$  cycles before proper device operation is achieved. Note that  $\overline{\text{RAS}}$  may be cycled during the initial pause. And any 8  $\overline{\text{RAS}}$  or  $\overline{\text{RAS}}/\overline{\text{CAS}}$  cycles are required after prolonged periods of  $\overline{\text{RAS}}$  inactivity before proper device operation is achieved.

7 : Measured with a load circuit equivalent to 2 TTL loads and 100pF.

8 : Assume that  $t_{\text{RCD}} \geq t_{\text{RCD}(\text{max})}$  and  $t_{\text{ASC}} \geq t_{\text{ASC}(\text{max})}$ .

9 : Assume that  $t_{\text{RCD}} \leq t_{\text{RCD}(\text{max})}$  and  $t_{\text{RAD}} \leq t_{\text{RAD}(\text{max})}$ .

10 : Assume that  $t_{\text{RAD}} \geq t_{\text{RAD}(\text{max})}$  and  $t_{\text{ASC}} \leq t_{\text{ASC}(\text{max})}$ .

11 : t<sub>OFF(max)</sub> define the time at which the output achieves the high impedance state ( $|I_{\text{out}}| \leq 10\ \mu\text{A}$  or  $20\ \mu\text{A}$ ) and are not reference to  $V_{\text{OH}(\text{min})}$  or  $V_{\text{OL}(\text{max})}$ .

TIMING REQUIREMENTS ( $T_a = 0 \sim 55^\circ\text{C}$ ,  $V_{CC} = 5\text{V} \pm 5\%$ ,  $\text{GND} = 0\text{V}$ ): (Note 12, 13)

Symbol	Parameter	Limits				Unit
		No. 2, No. 4, No. 6, No. 8		No. 1, No. 3, No. 5, No. 7		
		Min.	Max.	Min.	Max.	
t <sub>REF</sub>	Refresh cycle time (1024 cycles)		128		128	ms
t <sub>RP</sub>	$\overline{\text{RAS}}$ high pulse width	70		60		ns
t <sub>RCD</sub>	Delay time, $\overline{\text{RAS}}$ low to $\overline{\text{CAS}}$ low (Note 14)	20	50	20	43	ns
t <sub>CRP</sub>	Delay time, $\overline{\text{CAS}}$ high to $\overline{\text{RAS}}$ low (Note 15)	20		20		ns
t <sub>RPC</sub>	Precharge to $\overline{\text{CAS}}$ active time	0		0		ns
t <sub>CPN</sub>	$\overline{\text{CAS}}$ high pulse width	10		10		ns
t <sub>RAD</sub>	Column address delay time from $\overline{\text{RAS}}$ low (Note 16)	15	30	15	25	ns
t <sub>ASR</sub>	Row address setup time before $\overline{\text{RAS}}$ low	10		10		ns
t <sub>ASC</sub>	Column address setup time before $\overline{\text{CAS}}$ low (Note 17)	5	15	5	13	ns
t <sub>RAH</sub>	Row address hold time after $\overline{\text{RAS}}$ low	10		10		ns
t <sub>CAH</sub>	Column address hold time after $\overline{\text{CAS}}$ low	15		15		ns
t <sub>T</sub>	Transition time (Note 18)	3	50	3	50	ns

Note 12 : The timing requirements are assumed  $t_{\text{T}} = 5\text{ns}$ .

13 :  $V_{\text{IH}(\text{min})}$  and  $V_{\text{IL}(\text{max})}$  are reference levels for measuring timing of input signals.

14 : t<sub>RCD(max)</sub> is specified as a reference point only. If t<sub>RCD</sub> is greater than t<sub>RCD(max)</sub>, access time is defined as t<sub>CAC</sub> and t<sub>CAA</sub>.

15 : t<sub>CRP</sub> requirement is applicable for all  $\overline{\text{RAS}}/\overline{\text{CAS}}$  cycles.

16 : t<sub>RAD(max)</sub> is specified as reference point only. If  $t_{\text{RAD}} \geq t_{\text{RAD}(\text{max})}$  and  $t_{\text{ASC}} \leq t_{\text{ASC}(\text{max})}$ , access time is assumed by t<sub>CAA</sub> for read cycle.

17 : t<sub>ASC(max)</sub> is specified as a reference point only of address access time.

18 : t<sub>T</sub> is measured between  $V_{\text{IH}(\text{min})}$  and  $V_{\text{IL}(\text{max})}$ .

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Read and Refresh Cycles

Symbol	Parameter	Limits				Unit
		No. 2, No. 4, No. 6, No. 8		No. 1, No. 3, No. 5, No. 7		
		Min.	Max.	Min.	Max.	
tRC	Read cycle time	160		140		ns
tRAS	$\overline{\text{RAS}}$ low pulse width	80	10000	70	10000	ns
tCAS	$\overline{\text{CAS}}$ low pulse width	20	10000	20	10000	ns
tCSH	$\overline{\text{CAS}}$ hold time after $\overline{\text{RAS}}$ low	80		70		ns
tRSH	$\overline{\text{RAS}}$ hold time after $\overline{\text{CAS}}$ low	30		30		ns
tRCS	Read Setup time before $\overline{\text{CAS}}$ low	5		5		ns
tRCH	Read hold time after $\overline{\text{CAS}}$ high	0		0		ns
tRRH	Read hold time after $\overline{\text{RAS}}$ high	10		10		ns

Write Cycle (Early Write)

Symbol	Parameter	Limits				Unit
		No. 2, No. 4, No. 6, No. 8		No. 1, No. 3, No. 5, No. 7		
		Min.	Max.	Min.	Max.	
tWC	Write cycle time	160		140		ns
tRAS	$\overline{\text{RAS}}$ low pulse width	80	10000	70	10000	ns
tCAS	$\overline{\text{CAS}}$ low pulse width	20	10000	20	10000	ns
tCSH	$\overline{\text{CAS}}$ hold time after $\overline{\text{RAS}}$ low	80		70		ns
tRSH	$\overline{\text{RAS}}$ hold time after $\overline{\text{CAS}}$ low	30		30		ns
twCS	Write Setup time before $\overline{\text{CAS}}$ low	5		5		ns
twCH	Write hold time after $\overline{\text{CAS}}$ low	15		15		ns
tDS	Data setup time	10		10		ns
tDH	Data hold time after $\overline{\text{CAS}}$ low	25		25		ns

Page Mode Cycle (Read, Early Write)

Symbol	Parameter	Limits				Unit
		No. 2, No. 4, No. 6, No. 8		No. 1, No. 3, No. 5, No. 7		
		Min.	Max.	Min.	Max.	
tPC	Read, Write cycle time	60		55		ns
tCP	$\overline{\text{CAS}}$ high pulse width (Note 19)	10	20	10	18	ns
tRAS	$\overline{\text{RAS}}$ low pulse width	140	100000	125	100000	ns

Note 19 : tCP(max) is specified as a reference point only.

$\overline{\text{CAS}}$  before  $\overline{\text{RAS}}$  Refresh Cycle (Note 20)

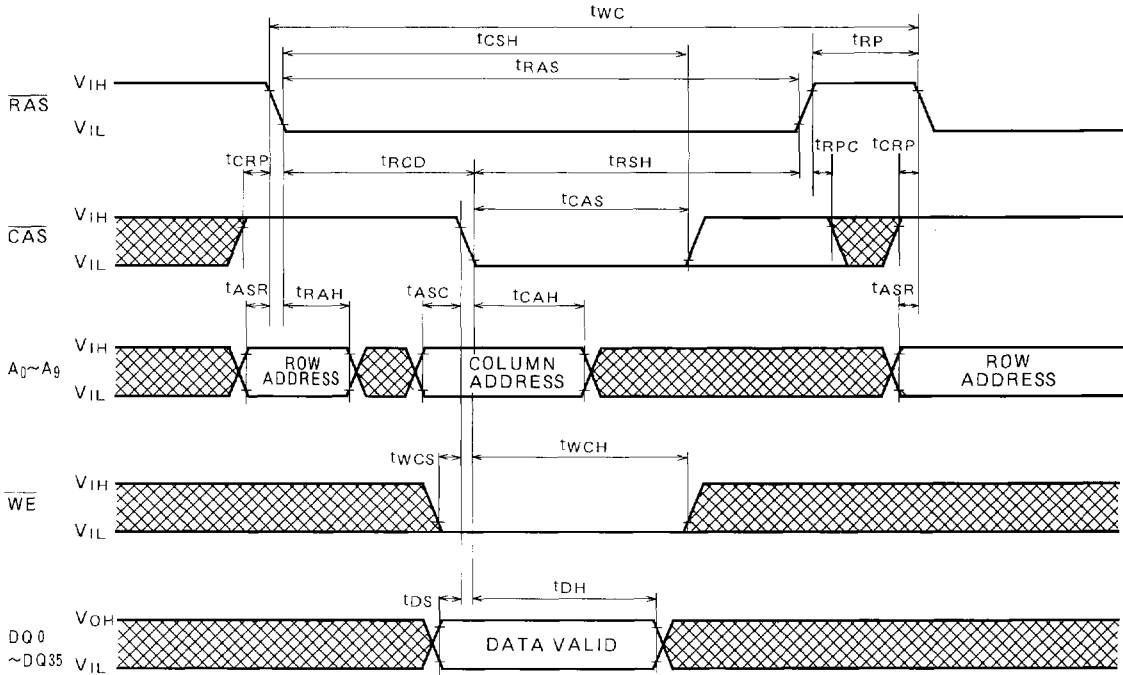
Symbol	Parameter	Limits		Unit
		Min.	Max.	
tCSR	$\overline{\text{CAS}}$ setup time for $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh	20		ns
tCHR	$\overline{\text{CAS}}$ hold time for $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh	15		ns

Note 20 : Eight or more  $\overline{\text{CAS}}$  before  $\overline{\text{RAS}}$  cycles are necessary for proper operation of  $\overline{\text{CAS}}$  before  $\overline{\text{RAS}}$  refresh mode.



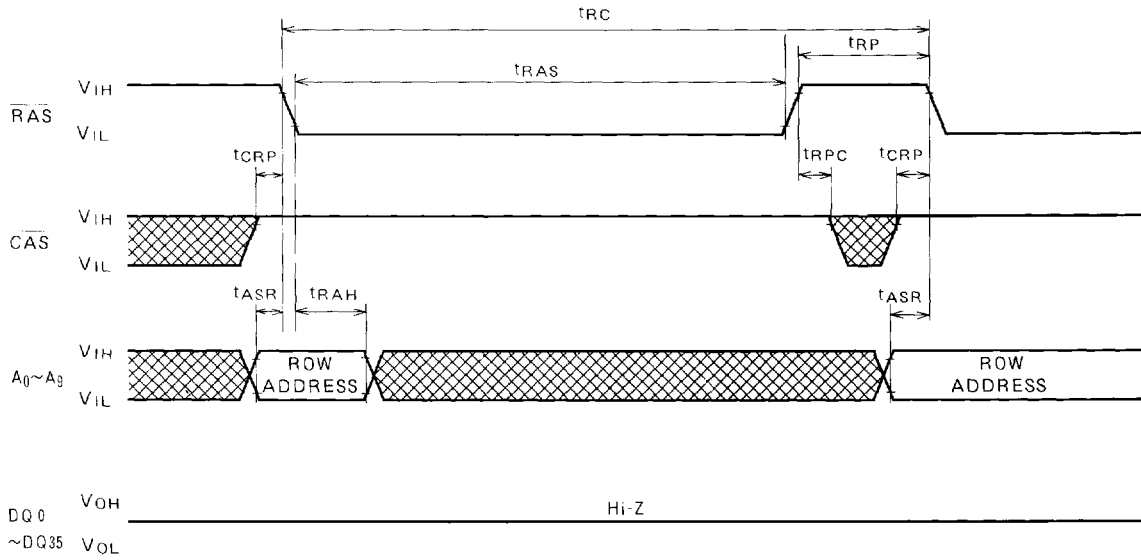


Early Write Cycle



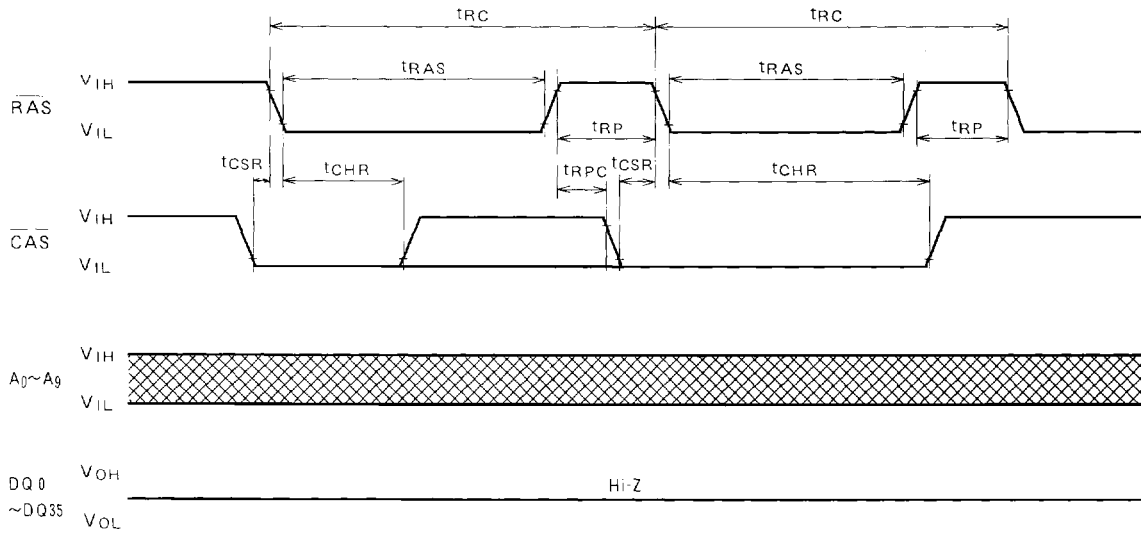
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**$\overline{\text{RAS}}$  only Refresh Cycle** (Note 22)



Note 22 :  $\overline{\text{WE}}$  = don't care.

**$\overline{\text{CAS}}$  before  $\overline{\text{RAS}}$  Refresh Cycle** (Note 23)



Note 23 :  $\overline{\text{WE}} = V_{IH}$



Page-Mode Early Write Cycle

